

1 mm MINI CARD GUIDE MB1 SERIES

Mates with:

(0,80mm) .031" PCB. (1,60mm) .062" PCB

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?MB1

Insulator Material: Black LCP Contact Material:

Plating: Sn or Au over 50μ" (1,27μm) Ni **Operating Temp Range:** -55°C to +125°C Insertion Depth: (5,26mm)

.207" to (6,10mm) .240' RoHS Compliant:

Processing:

Max Processing Temp: 230°C for 60 seconds, or 260°C for 20 seconds 3x Lead-Free Solderable:

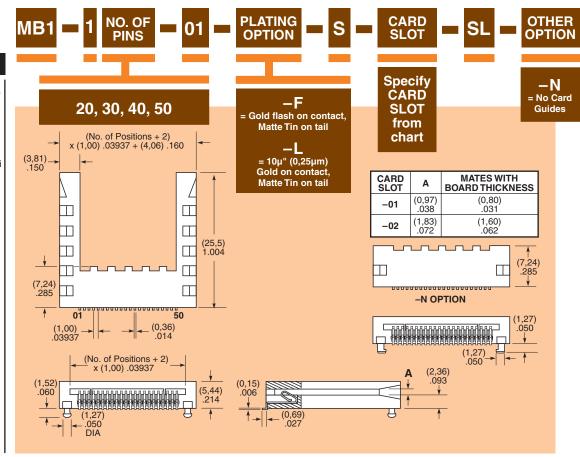
SMT Lead Coplanarity: (0,10mm) .004" max (20-30) (0,15mm) .006" max (40-50)

Important Note:

Samtec recommends that pads on the mating board be Gold plated.

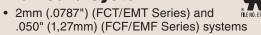
Note: Other Gold plating options available. Contact Samtec.

Some sizes, styles and options are non-standard. non-returnable.

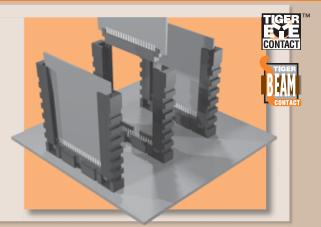


ALSO AVAILABLE

Flex Card System



- Vertical and horizontal
- Header with snap-on card guides for design flexibility
- Elevated design now available
- PCMCIA (PCMT/PCMS Series) Compact Flash (CFT/CFS Series) compatible applications available
- Ideal for multiple add-on cards
- Solder locks for mechanical stability
- Any size from 40 to 100 contacts



Due to technical progress, all designs, specifications and components are subject to change without notice.

WWW.SAMTEC.COM